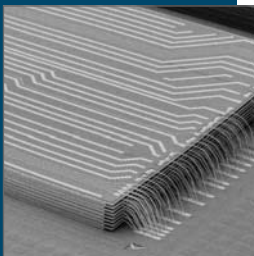
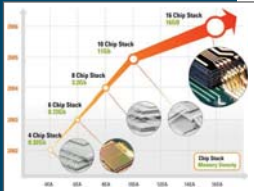


# Advanced Packaging Update: Market and Technology Trends

Vol. 4, 2006



Volume 4 of the Advanced Packaging Update for 2006 features special coverage of the market with a forecast for units of BGAs and CSPs by package construction. The BGA market is divided into plastic, tape, and ceramic structures. The CSP market is divided into laminate, flex circuit, and leadframe substrates. Unit growth projections are also provided for stacked CSP and package-on-package (PoP) shipments. Examples of products with stacked die CSPs and PoP are included. A market growth analysis based on input from both captive and merchant assembly operations is provided. Key applications and drivers for unit volume and revenue growth are highlighted. Trends in memory packaging are described and roadmaps from various companies are provided.

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